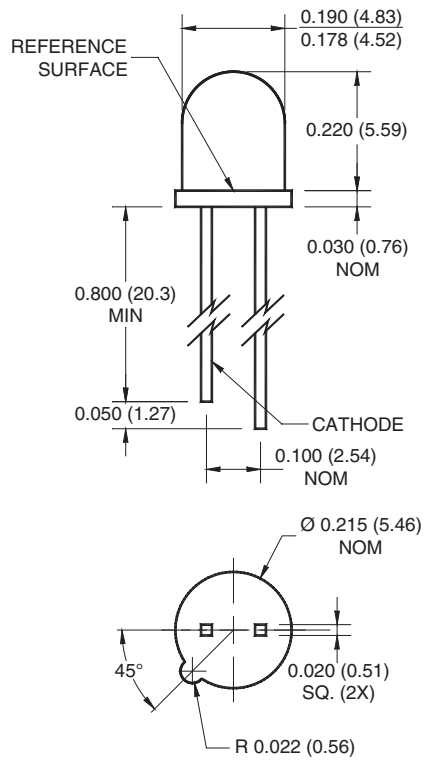
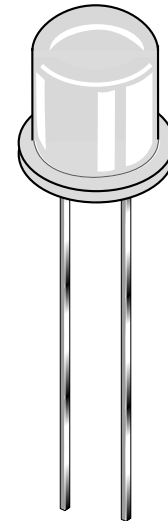


**PACKAGE DIMENSIONS**

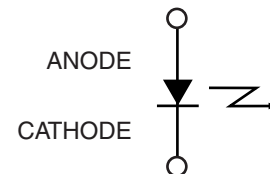


**NOTES:**

1. Dimensions for all drawings are in inches (mm).
2. Tolerance of  $\pm .010$  (.25) on all non-nominal dimensions unless otherwise specified.



**SCHEMATIC**



**DESCRIPTION**

The QED422/423 is an 880 nm AlGaAs LED encapsulated in a clear, purple tinted, plastic TO-46 package.

**FEATURES**

- $\lambda = 880$  nm
- Chip material = AlGaAs
- Package type: Plastic TO-46
- Matched Photosensor: QSD722/723/724
- Medium Wide Emission Angle, 30°
- High Output Power
- Package material and color: clear, purple tinted, plastic

**QED422 QED423**

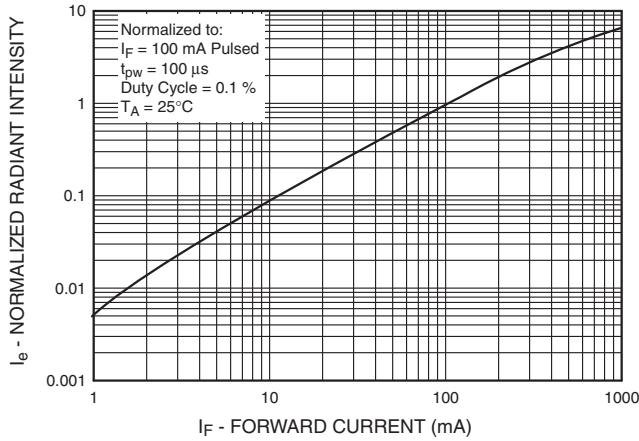
<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_A = 25^\circ\text{C}$ unless otherwise specified)			
Parameter	Symbol	Rating	Unit
Operating Temperature	$T_{\text{OPR}}$	-40 to + 100	$^\circ\text{C}$
Storage Temperature	$T_{\text{STG}}$	-40 to + 100	$^\circ\text{C}$
Soldering Temperature (Iron) <sup>(2,3,4)</sup>	$T_{\text{SOL-I}}$	240 for 5 sec	$^\circ\text{C}$
Soldering Temperature (Flow) <sup>(2,3)</sup>	$T_{\text{SOL-F}}$	260 for 10 sec	$^\circ\text{C}$
Continuous Forward Current	$I_F$	100	mA
Reverse Voltage	$V_R$	5	V
Power Dissipation <sup>(1)</sup>	$P_D$	200	mW

**NOTES:**

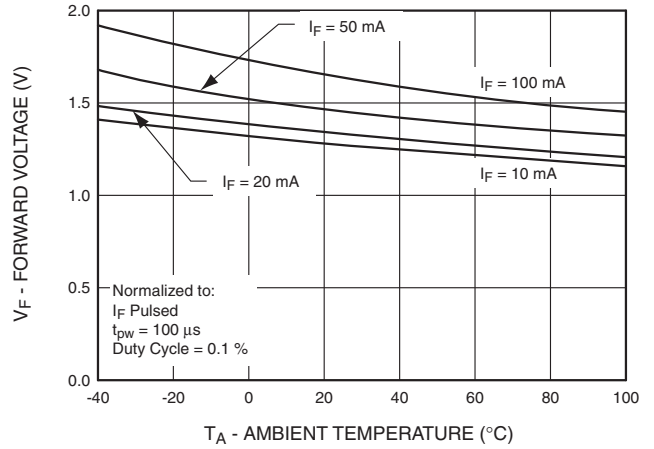
1. Derate power dissipation linearly 2.67 mW/ $^\circ\text{C}$  above 25 $^\circ\text{C}$ .
2. RMA flux is recommended.
3. Methanol or isopropyl alcohols are recommended as cleaning agents.
4. Soldering iron 1/16" (1.6 mm) minimum from housing

<b>ELECTRICAL / OPTICAL CHARACTERISTICS</b> ( $T_A = 25^\circ\text{C}$ )						
Parameter	Test Conditions	Symbol	Min	Typ	Max	Units
Peak Emission Wavelength	$I_F = 100 \text{ mA}$	$\lambda_{\text{PE}}$	—	880	—	nm
Emission Angle	$I_F = 100 \text{ mA}$	$2\theta_{1/2}$	—	30	—	Deg.
Forward Voltage	$I_F = 100 \text{ mA}$ , $t_p = 20 \text{ ms}$	$V_F$	—	—	1.8	V
Reverse Current	$V_R = 5 \text{ V}$	$I_R$	—	—	10	$\mu\text{A}$
Radiant Intensity QEC522	$I_F = 100 \text{ mA}$ , $t_p = 20 \text{ ms}$	$I_E$	10	—	40	mW/sr
Radiant Intensity QEC523	$I_F = 100 \text{ mA}$ , $t_p = 20 \text{ ms}$	$I_E$	20	—	—	mW/sr
Rise Time	$I_F = 100 \text{ mA}$	$t_r$	—	800	—	ns
Fall Time		$t_f$	—	800	—	ns

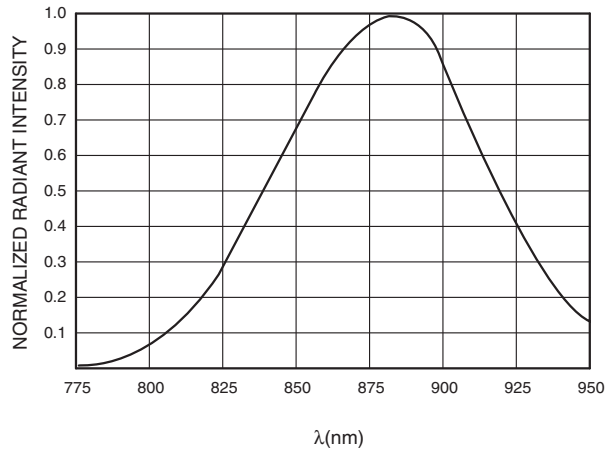
**Fig. 1 Normalized Radiant Intensity vs. Forward Current**



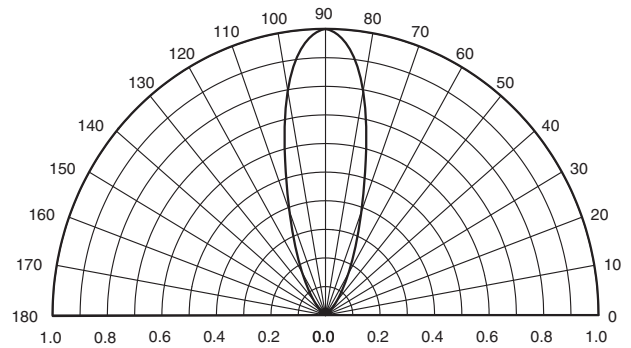
**Fig. 2 Forward Voltage vs. Ambient Temperature**



**Fig. 3 Normalized Radiant Intensity vs. Wavelength**



**Fig. 4 Radiation Diagram**



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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.